

UNITED STATES PATENT AND TRADEMARK OFFICE

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BEFORE THE PATENT TRIAL AND APPEAL BOARD

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US CONEC LTD.,  
Petitioner

v.

SENKO ADVANCED COMPONENTS, INC.,  
Patent Owner

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Case IPR2024-00120  
U.S. Patent No. 10,191,230

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**JOINT MOTION TO TERMINATE *INTER PARTES* REVIEW**

***Mail Stop "PATENT BOARD"***  
Patent Trial and Appeal Board  
U.S. Patent and Trademark Office  
P.O. Box 1450  
Alexandria, VA 22313-1450

**PETITIONER’S UPDATED EXHIBIT LIST**

| <b>Exhibit Number</b> | <b>Description</b>                                                                                                                                                                                                                                                                                            |
|-----------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| <b>1001</b>           | U.S. Patent No. 10,191,230 to Wong et al. (“’230 Patent”), including U.S. Patent No. 10,191,230’s Reexamination Certificate                                                                                                                                                                                   |
| <b>1002</b>           | File History for U.S. Patent Application No. 15/884,327, issued as U.S. Patent No. 10,191,230                                                                                                                                                                                                                 |
| <b>1003</b>           | File History for U.S. Patent Application No. 90/014,456 for reexamined U.S. Patent No. 10,191,230                                                                                                                                                                                                             |
| <b>1004</b>           | Declaration of William Singhose, Ph.D.                                                                                                                                                                                                                                                                        |
| <b>1005</b>           | <i>Intentionally Left Blank</i>                                                                                                                                                                                                                                                                               |
| <b>1006</b>           | <i>Curriculum Vitae</i> of William Singhose, Ph.D.                                                                                                                                                                                                                                                            |
| <b>1007</b>           | U.S. Patent No. 9,684,130 to Veatch et al. (“Veatch”)                                                                                                                                                                                                                                                         |
| <b>1008</b>           | U.S. Publication No. 2017/0343740 to Nguyen (“Nguyen”)                                                                                                                                                                                                                                                        |
| <b>1009</b>           | PCT Publication No. WO 2017/127208 to Lee (“Lee”)                                                                                                                                                                                                                                                             |
| <b>1010</b>           | U.S. Publication No. 2017/0363818 to Suzic (“Suzic”)                                                                                                                                                                                                                                                          |
| <b>1011</b>           | U.S. Publication No. 2012/0177326 to Peng (“Peng”)                                                                                                                                                                                                                                                            |
| <b>1012</b>           | U.S. Patent No. 8,061,906 to Nehler (“Nehler”)                                                                                                                                                                                                                                                                |
| <b>1013</b>           | U.S. Patent No. 8,834,038 to Limbert (“Limbert”)                                                                                                                                                                                                                                                              |
| <b>1014</b>           | Norton, “Machine Design: An Integrated Approach, Third Edition,” Pearson Education, Inc. 2006. (“Norton”)                                                                                                                                                                                                     |
| <b>1015</b>           | Kordz, “RJ45 CAT6 Field Termination Connector & Strain Relief,” Technical Data Sheet, accessed at <a href="https://futurereadysolutions.com/wp-content/uploads/ONE-RJ45-Connectors-Datasheet-190107.0.pdf">https://futurereadysolutions.com/wp-content/uploads/ONE-RJ45-Connectors-Datasheet-190107.0.pdf</a> |
| <b>1016</b>           | U.S. Publication No. 2004/0043654 to Lee et al. (“Lee’654”)                                                                                                                                                                                                                                                   |
| <b>1017</b>           | U.S. Publication No. 2013/0122745 to Soubh (“Soubh”)                                                                                                                                                                                                                                                          |
| <b>1018</b>           | U.S. Patent No. 5,915,058 to Clairardin et al. (“Clairardin”)                                                                                                                                                                                                                                                 |
| <b>1019</b>           | U.S. Patent No. 5,719,977 to Lampert et al. (“Lampert”)                                                                                                                                                                                                                                                       |

| <b>Exhibit<br/>Number</b> | <b>Description</b>                                                                                                                                                                                                                                                     |
|---------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| <b>1020</b>               | Order Staying Case, <i>Senko Advanced Components, Inc. v. US Conec, Ltd.</i> , No. 1:23-cv-00083-JPM (D. Del.), July 6, 2023                                                                                                                                           |
| <b>1021</b>               | Google Data Centers Gallery, accessed at <a href="https://www.google.com/about/datacenters/gallery/">https://www.google.com/about/datacenters/gallery/</a>                                                                                                             |
| <b>1022</b>               | “19-Inch Rack,” Lite-On, accessed at <a href="https://liteon-cips.com/products/racks/19-inch-rack/">https://liteon-cips.com/products/racks/19-inch-rack/</a>                                                                                                           |
| <b>1023</b>               | “Fiber Optic Rack Mount Enclosure, 3-Panel 1 RMS,” Computer Cable Store, accessed at <a href="https://www.computercablestore.com/fiber-optic-rack-mount-enclosure-3-panel-1-rms">https://www.computercablestore.com/fiber-optic-rack-mount-enclosure-3-panel-1-rms</a> |
| <b>1024</b>               | “What Is Optical Fiber Technology, and How Does It Work?,” NAI, accessed at <a href="https://www.nai-group.com/optical-fiber-technology-how-it-works/">https://www.nai-group.com/optical-fiber-technology-how-it-works/</a>                                            |
| <b>1025</b>               | “Fiber Optic Adapter/Coupler Tutorial,” FS Community, accessed at <a href="https://community.fs.com/blog/fiber-optic-adaptercoupler-tutorial.html">https://community.fs.com/blog/fiber-optic-adaptercoupler-tutorial.html</a>                                          |
| <b>1026</b>               | “HDI-45 Connector,” Wikipedia, accessed at <a href="https://en.wikipedia.org/wiki/HDI-45_connector">https://en.wikipedia.org/wiki/HDI-45_connector</a>                                                                                                                 |
| <b>1027</b>               | Settlement Agreement (Confidential)                                                                                                                                                                                                                                    |

Pursuant to 37 C.F.R. § 42.74 and the authorization provided by the Board,  
Pursuant to 35 U.S.C. § 317(b) and 37 C.F.R. § 42.74(c), Petitioner US Conec Ltd.  
("Petitioner") and Patent Owner Senko Advanced Components, Inc. ("Patent  
Owner") (collectively, the "Parties") jointly request termination of this proceeding,  
IPR2024-00120, directed to U.S. Patent No. 10,191,230 ("the '230 patent").

Petitioner and Patent Owner are currently submitting a true copy of any  
agreement or understanding between Petitioner and Patent Owner made in  
connection with, or in contemplation of, the termination of the proceeding under  
37 C.F.R. § 42.74(b) with this joint motion. The Parties further jointly certify that  
there are no further agreements or understandings, oral or written, between them,  
including any collateral agreements, made in connection with, or in contemplation  
of, the termination of this proceeding as set forth in 35 U.S.C. § 317(b). The  
Parties request that any agreement or understanding submitted be maintained as  
business confidential under 37 C.F.R. § 42.74(c), and are concurrently filing a  
separate joint request to this effect.

Petitioner and Patent Owner have resolved their disputes regarding the '230  
patent, including both in this proceeding and Patent Owner's assertion of the '230  
patent in the related district court litigation, *Senko Advanced Components, Inc. v.*  
*US Conec Ltd.*, 1:23-cv-00083 (D. Del.). The parties do not anticipate further  
litigation between them concerning the '230 patent. The following proceedings

involving the parties are currently pending before the Board and have been instituted: IPR2024-00115, IPR2024-00116, IPR2024-00117, IPR2024-00118, IPR2024-00119, IPR2024-00121. The following proceedings involving the parties are currently pending before the Board and have not been instituted: IPR2024-00805, PGR2024-00032, PGR2024-00037, IPR2024-01074. Institution was denied in IPR2024-00122, involving the parties, and Petitioner has submitted a rehearing request. The '230 patent is not involved in these other pending proceedings.

## **I. STATEMENT OF RELIEF REQUESTED**

As authorized by the Board, the parties are jointly and contemporaneously filing: (i) this joint motion to terminate the proceeding; (ii) a true copy of any agreement or understanding between Petitioner and Patent Owner made in connection with, or in contemplation of, the requested termination of the Petition; and (iii) a joint request to treat the agreement as business confidential information and keep the agreement separate from the file of the involved patent, pursuant to 37 C.F.R. § 42.74(c).

Petitioner and Patent Owner jointly request that the Board terminate this proceeding in its entirety. Termination is appropriate at this stage and in view of a settlement between Petitioner and Patent Owner. An *inter partes* review shall be terminated with respect to any petitioner upon the joint request of the petitioner and the patent owner, unless the Office has decided the merits of the proceedings

before the request for termination is filed. 35 U.S.C. § 317(a); *see also* 2019

Consolidated Patent Office Trial Practice Guidelines, p. 86 (“[T]here are strong public policy reasons to favor settlement between the parties . . . . The Board expects that a proceeding will terminate . . . unless the Board has already decided the merits of the proceeding.”). Good cause exists to terminate this proceeding because (1) Petitioner and Patent Owner have resolved their disputes regarding the ’230 patent; (3) this proceeding is still at an early stage because the Office has not yet decided the merits of the proceedings; and (4) terminating the proceeding now would thus serve the interests of judicial economy as well as the mutual interest of the parties.

## II. CONCLUSION

Petitioner and Patent Owner respectfully request that the Board grant the parties' Joint Motion to Terminate this proceeding in its entirety. This joint pleading is being filed by the Petitioner, with the consent of the Patent Owner.

Respectfully submitted,

STERNE, KESSLER, GOLDSTEIN & FOX PLLC

/Jason D. Eisenberg/

Jason D. Eisenberg  
Registration No. 43,447  
*Counsel for Petitioner US Conec Ltd.*

Date: August 27, 2024

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**CERTIFICATE OF SERVICE (37 C.F.R. § 42.6(e)(1))**

The undersigned certifies that true and correct copies of the foregoing  
**JOINT MOTION TO TERMINATE *INTER PARTES* REVIEW** and  
**EXHIBIT 1027 (CONFIDENTIAL)** were served in their entireties electronically  
via e-mail on August 27, 2024, on the following counsel of record for Patent

Owner:

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Respectfully submitted,  
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